

New Application
Docket No.: 32860-000302/US

2. (Amended) The component of claim 1, wherein the edge of the glass cover has been superficially roughened.

3. (Amended) The component of claim 1, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

4. (Amended) The component of claim 3, wherein the adhesive is UV-curable.

5. (Amended) The component of claim 3, wherein the adhesive is an epoxy resin.

6. (Amended) A process for producing a component, comprising:

producing a plurality of recesses in a glass plate by three-dimensional removal of material using a blasting method using commercial crystal corundum having an average particle size of 30 μm and a blasting pressure of 5 bar, said recesses having edges protected by a resist layer;

removing the protective layer of the edge; and

subjecting the edges of the recesses, lying bare, to a further blasting method using corundum having an average particle size of 9 μm and a blasting pressure of only 3 bar.

7. (Amended) The process of claim 6, wherein an injector blasting nozzle is used as blasting nozzle in the initial blasting method.

8. (Amended) The process of claim 6, wherein the distance between nozzle and workpiece in the initial blasting method is 80 mm.

9. The process of claim 6, wherein edges having a roughness of about 30 rms are produced in the further blasting method in a blasting time of 30 seconds.

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10. (Amended) The process of claim 6, wherein after the recesses have been manufactured, the glass plate is used in order to encapsulate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate, and wherein, following the encapsulation, the resultant components are at least partly individualized.

Please add the following new claims

- 11. The process of claim 6, further comprising:
 - encapsulating a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate using the glass plate, wherein the subsequently resulting components are at least partly individualized.
- 12. The component of claim 2, wherein the glass cover is bonded to the glass substrate using an organic adhesive.
- 13. The component of claim 12, wherein the adhesive is UV-curable.
- 14. The component of claim 4, wherein the adhesive is an epoxy resin.
- 15. The component of claim 12, wherein the adhesive is an epoxy resin.
- 16. The component of claim 13, wherein the adhesive is an epoxy resin.
- 17. The process of claim 6, wherein the component includes a glass substrate, an organic light-emitting diode arranged on said glass substrate, and a glass cover, arranged over the organic light-emitting diode and glued at an edge to the glass substrate, said cover being produced from a glass plate by the three-dimensional removal of material using the blasting method.
- 18. The process of claim 6, wherein the glass cover is bonded to the glass substrate using an organic adhesive.
- 19. The process of claim 18, wherein the adhesive is UV-curable.